



Device Material Content

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Package: 256 ftBGA (option 3)
Total Device Weight 0.803 Grams

Package Code:

BFG256

Products:

XO4

Assembly: ASEKH

Size (mm): 17 x 17

Lead pitch (mm): 1.0

MSL: 3

Reflow max (°C): 260

July, 2026

	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Substance	CAS #	% of Subst.	Notes / Assumptions:
Die	1.390%	0.0112	1.390%	0.0112	Silicon chip	7440-21-3	100.00%	
Mold Compound	54.236%	0.4353	47.457% 3.525% 2.983% 0.271%	0.3809 0.0283 0.0239 0.0022	Silica Epoxy resin Phenol Resin Carbon Black	60676-86-0 - - 1333-86-4	87.50% 6.50% 5.50% 0.50%	Mold Compound: Kyocera KEG-2250LKDS (ULA)
D/A Epoxy	0.200%	0.0016	0.172% 0.012% 0.010% 0.002% 0.004% 0.0004%	0.00138 0.00010 0.00008 0.00002 0.00003 0.000003	Silver (Ag) 2,2-dimethyl-1,3 Propanediyl Bismethacrylate A mixture of: 4-allyl-2,6-bis(2,3-epoxypropyl)phenol Perfluoropolyoxyalkane ether 2-[[[2,2 bis[[[1-oxoallyloxy]methyl]butoxy]methyl]-2-ethyl-1,3-propanediyl diacrylate bis(4-tert-butylcyclohexyl) peroxydicarbonate	7440-22-4 1985-51-9 - 925918-64-5 94108-97-1 15520-11-3	86.09% 5.92% 4.92% 1.00% 1.88% 0.19%	Die attach epoxy: Henkel (Ablebond) 2100A
Wire	0.190%	0.00153	0.187% 0.003%	0.00150 0.00002	Copper Palladium	7440-50-8 7440-05-3	98.50% 1.50%	0.8 mil diameter; 1 wire per solder ball
Solder Balls	15.492%	0.1243	15.259% 0.155% 0.077%	0.1225 0.0012 0.0006	Tin (Sn) Silver (Ag) Copper (Cu)	7440-31-5 7440-22-4 7440-50-8	98.50% 1.00% 0.50%	SAC105
Substrate	13.021%	0.1045	8.855% 4.167%	0.0711 0.0334	Glass fiber BT Resins	65997-17-3 -	68.00% 32.00%	BT Resin CCL-HL832NX-A
Foil	9.500%	0.0762	8.089% 1.356% 0.054%	0.0649 0.0109 0.0004	Copper Nickel Gold	7440-50-8 7440-02-0 7440-57-5	85.15% 14.28% 0.57%	
Solder Mask	5.971%	0.0479	3.356% 0.955% 1.314% 0.179% 0.167%	0.0269 0.0077 0.0105 0.0014 0.0013	Quartz 3-methoxy-3-methylbutylacetate Barium Sulfate Talc (containing no asbestiform fibers) Trade secret ingredients	14808-60-7 103429-90-9 7727-43-7 14807-96-6 -	56.20% 16.00% 22.00% 3.00% 2.80%	Solder mask PSR4000 AUS 308

100.000%

0.803

100.000%

0.803

800.0%

Notes:

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Rev. A